

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSB012NE2LXI	**Issued**	11. November 2019
MA#	MA001050800		
Package	MG-WDSON-2-8	**Weight***	82.84 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.494	4.22	4.22	42179	42179
leadframe	non noble metal	copper	7440-50-8	74.415	89.84	89.84	898299	898299
leadfinish	non noble metal	nickel	7440-02-0	0.211	0.25		2549	
	noble metal	silver	7440-22-4	0.840	1.01	1.26	10140	12689
plating	non noble metal	nickel	7440-02-0	0.211	0.25	0.25	2549	2549
solder	non noble metal	copper	7440-50-8	0.011	0.01		133	
	noble metal	silver	7440-22-4	0.066	0.08		795	
	non noble metal	tin	7440-31-5	2.119	2.56	2.65	25574	26502
glue	plastics	acrylic resin	-	0.160	0.19		1936	
	noble metal	silver	7440-22-4	0.985	1.19	1.38	11894	13830
passivation	plastics	epoxy resin	-	0.327	0.40	0.40	3952	3952
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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